

## Лекція 6

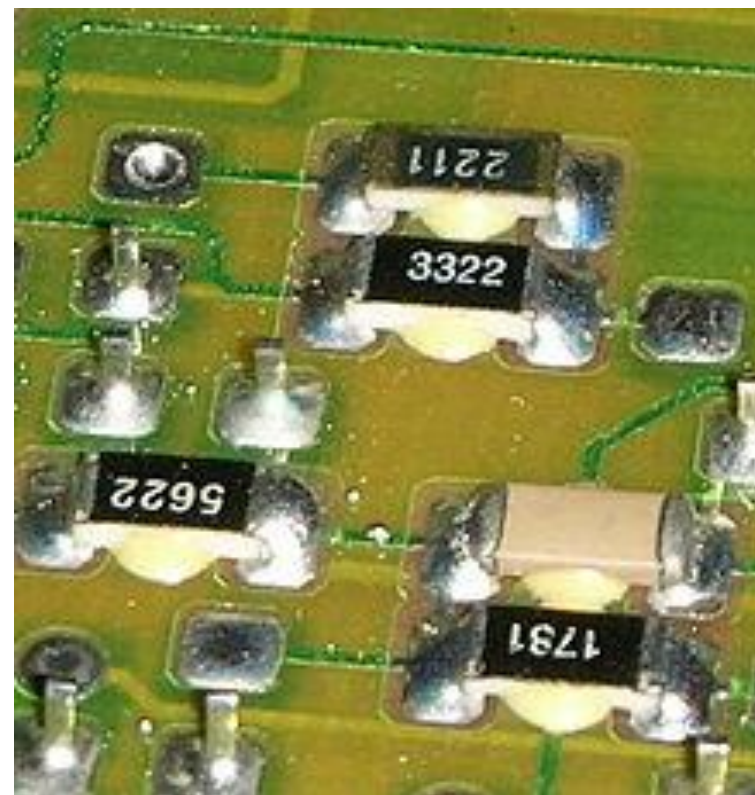
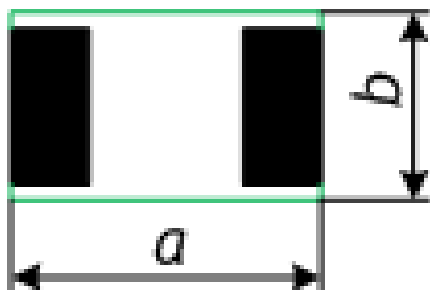
# Корпуси електрорадіоелементів



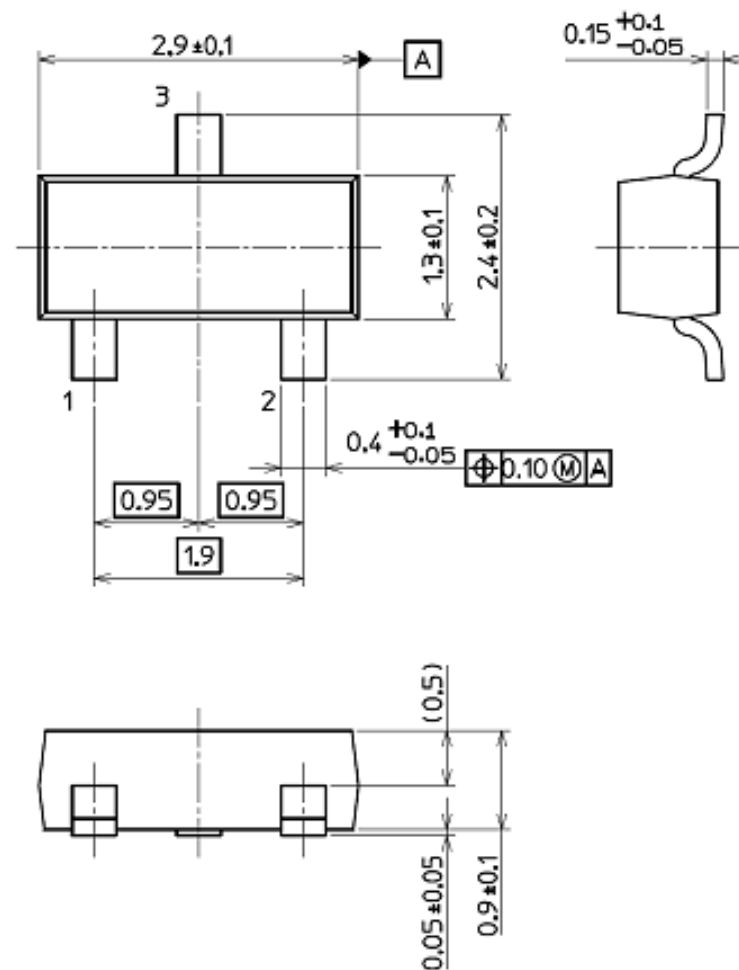
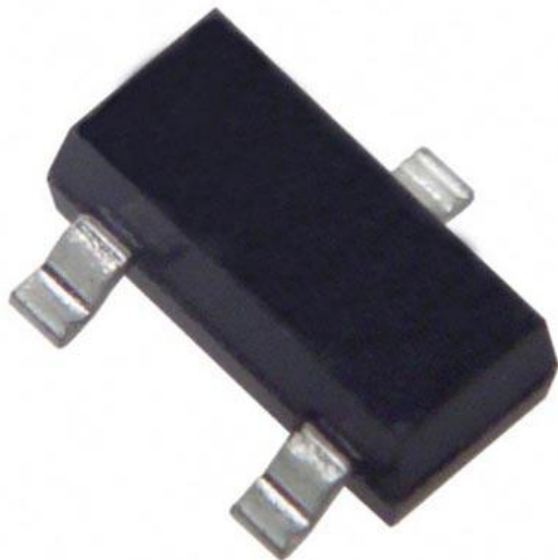
Два основних види монтажу: поверхневий (SMD) та наскрізний.

*a*    *b*

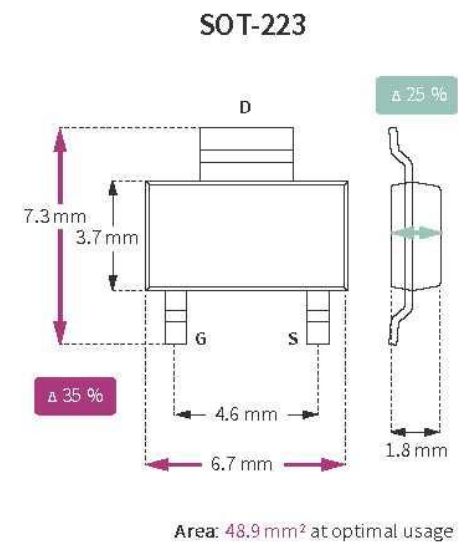
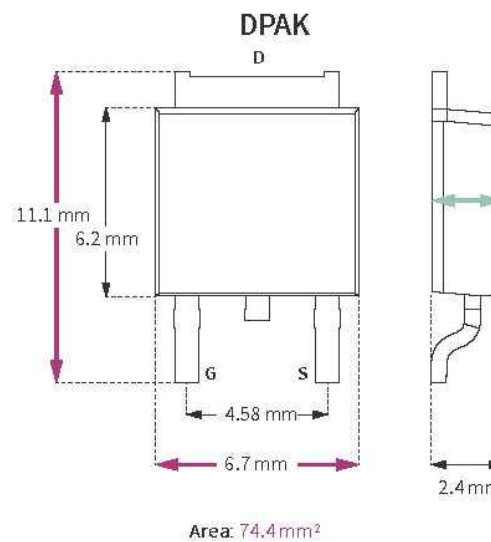
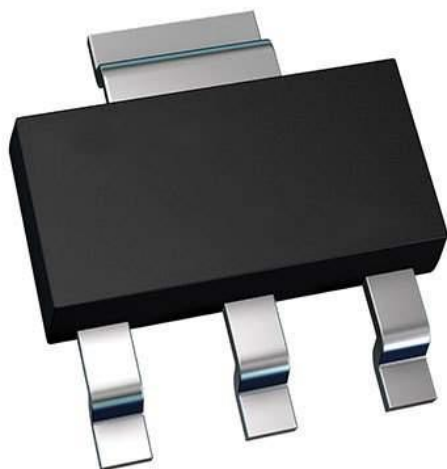
- 0,4 × 0,2 мм (дюймовий типорозмір – 01005);
- 0,6 × 0,3 мм (0201);
- 1,0 × 0,5 мм (0402);
- 1,6 × 0,8 мм (0603);
- 2,0 × 1,25 мм (0805);
- 3,2 × 1,6 мм (1206);
- 3,2 × 2,5 мм (1210);
- 4,5 × 3,2 мм (1812);
- 4,5 × 6,4 мм (1825);
- 5,6 × 5,0 мм (2220);
- 5,6 × 6,3 мм (2225);



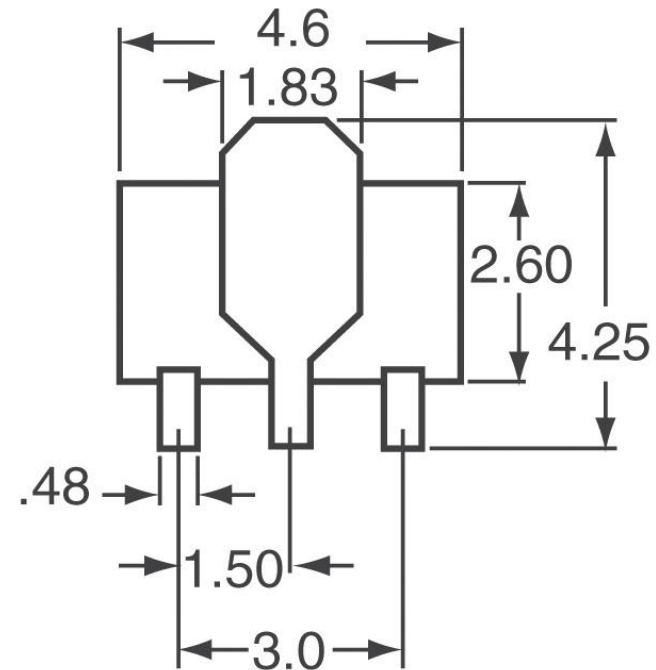
SOT23 (Small Outline Transistor) / TO236 / SC59



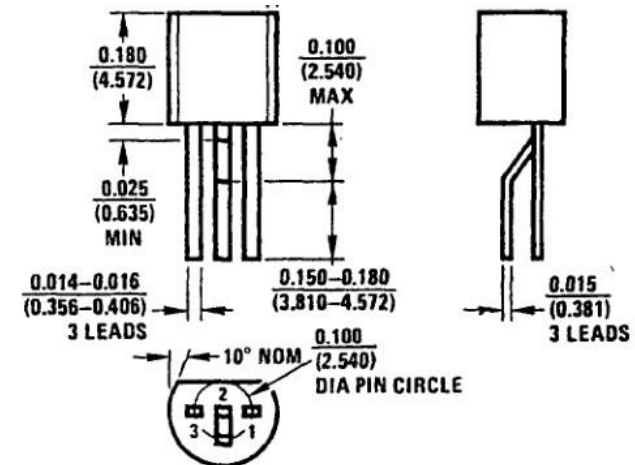
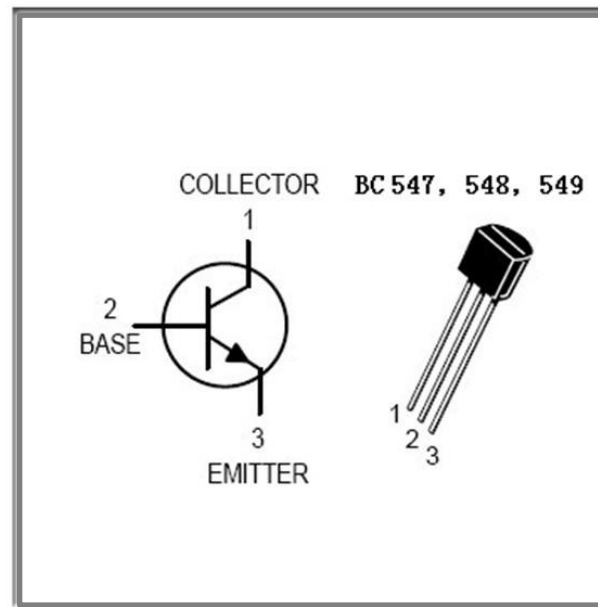
SOT-223 / TO261 / SC73



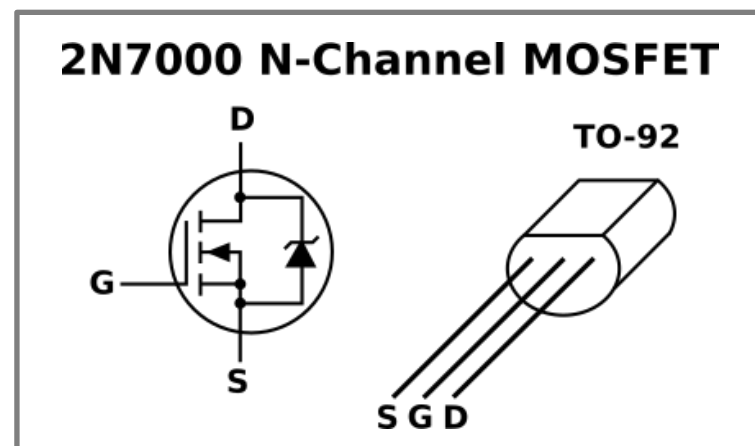
SOT-89 / TO243 / HSOP-3 / SC62



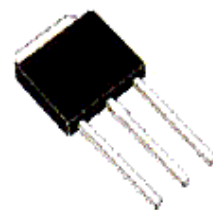
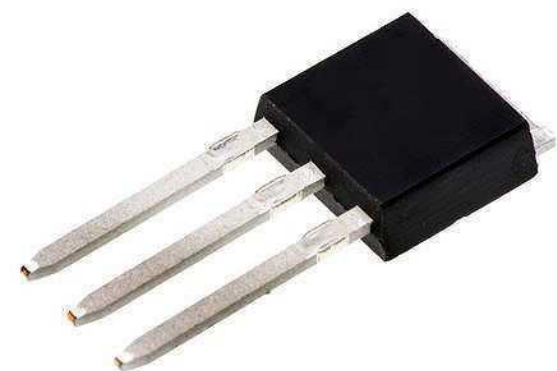
TO-92 / TO226



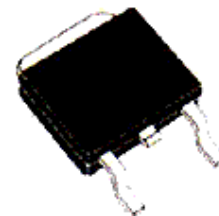
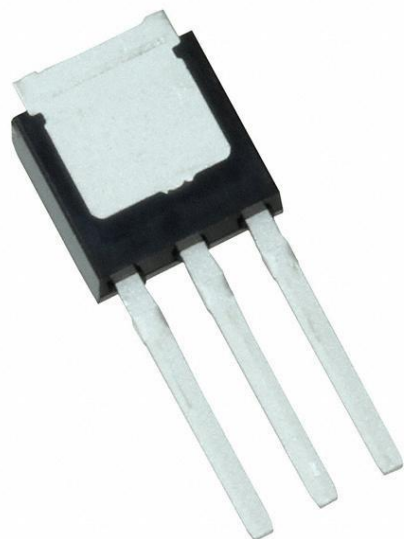
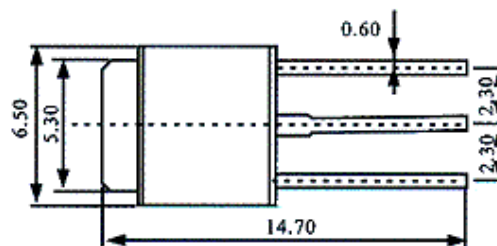
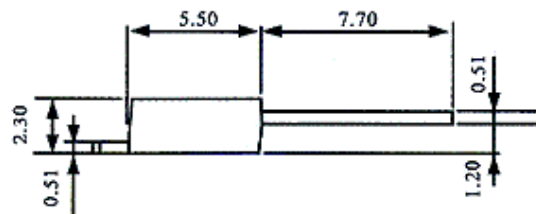
NS Package Z03D  
3-Lead TO-92 Plastic Package (Z)



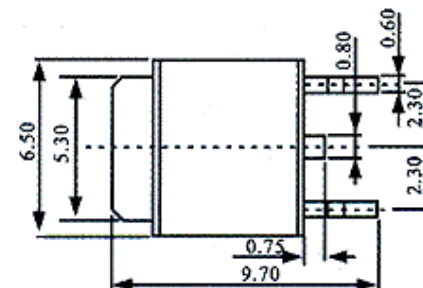
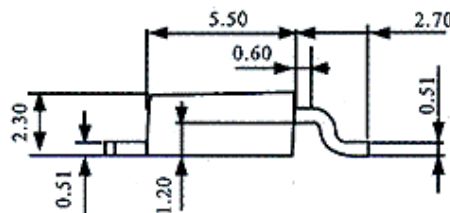
TO-251 / TO - 252



TO-251

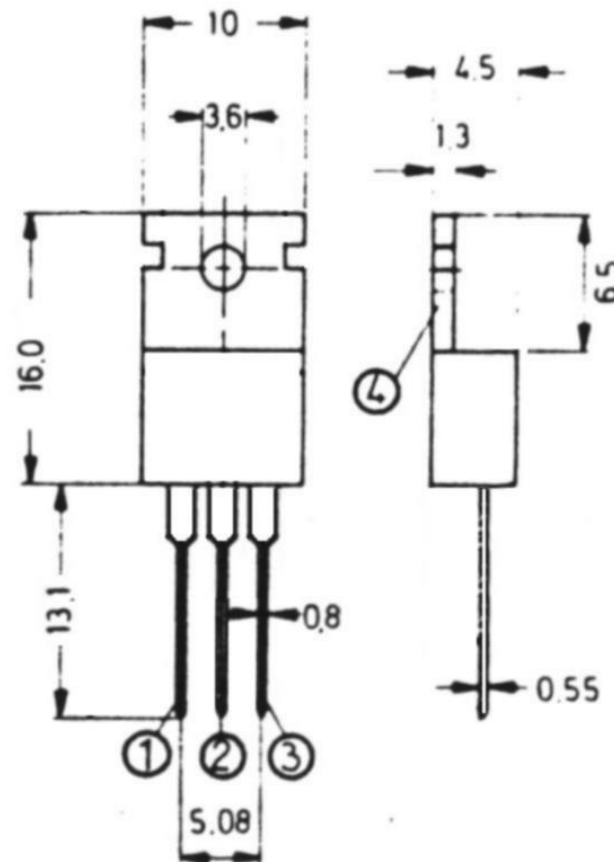
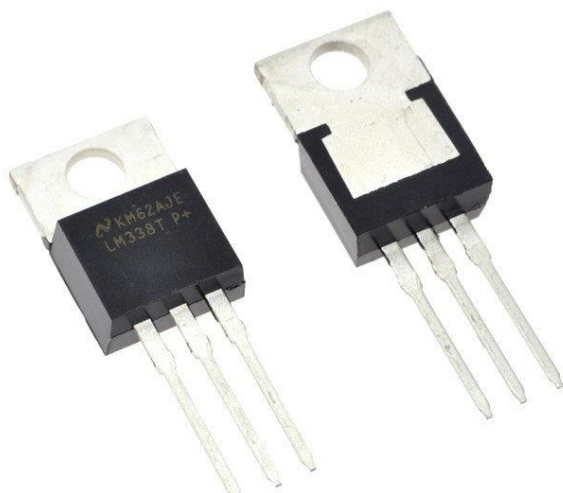


TO-252



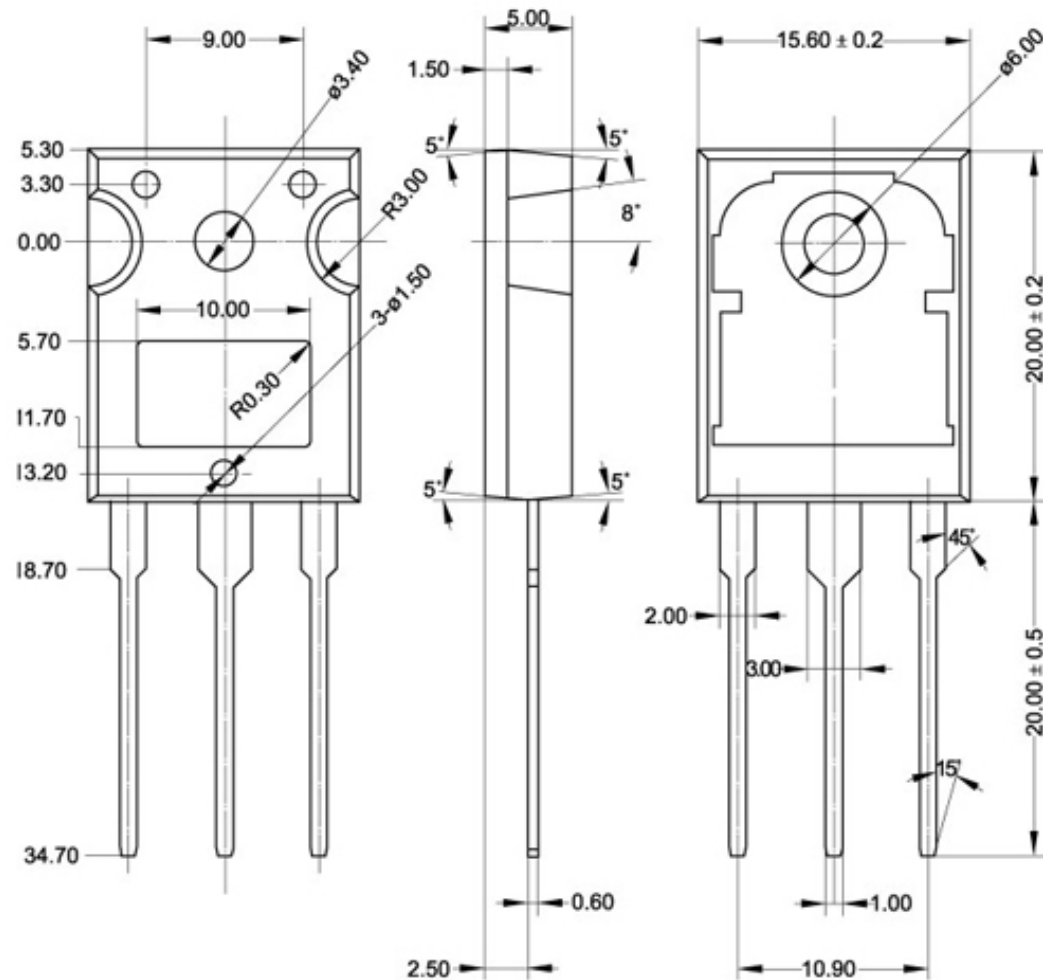


ТО-220



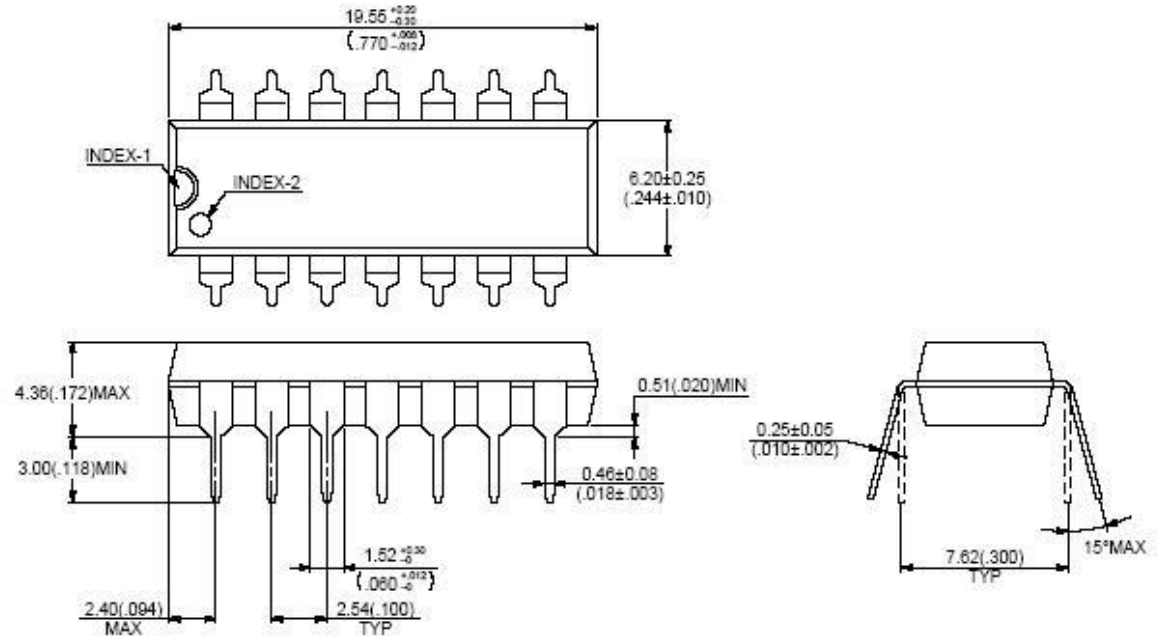
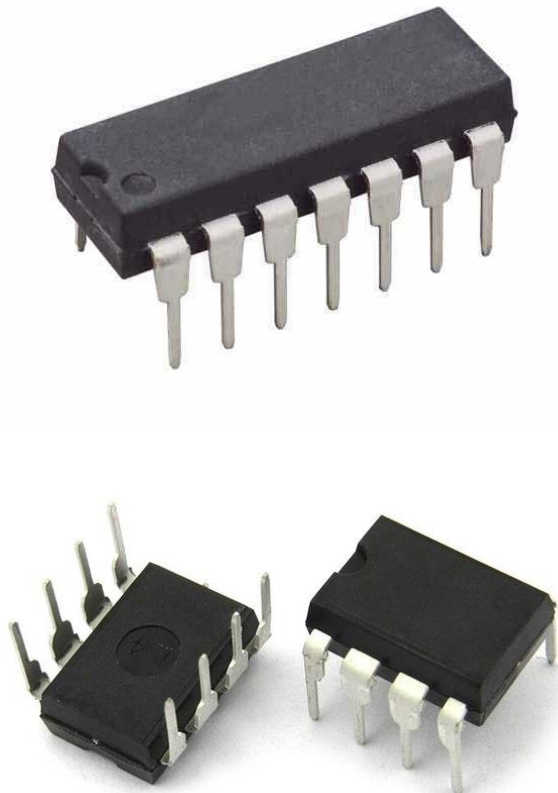
**TO-220**

ТО-247

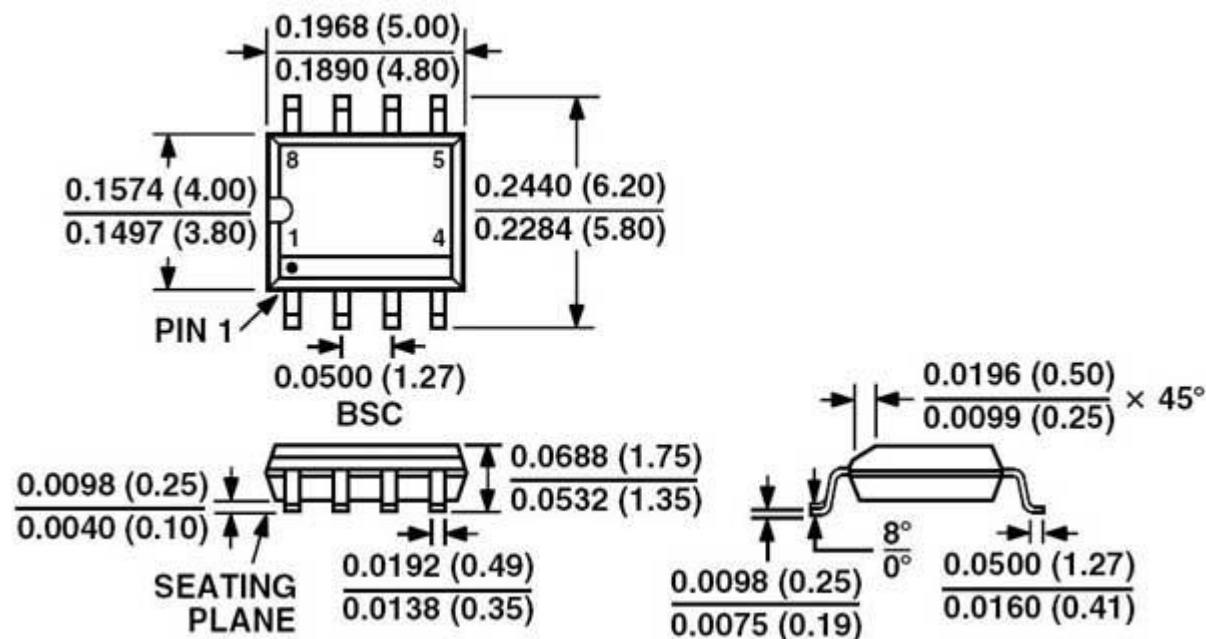
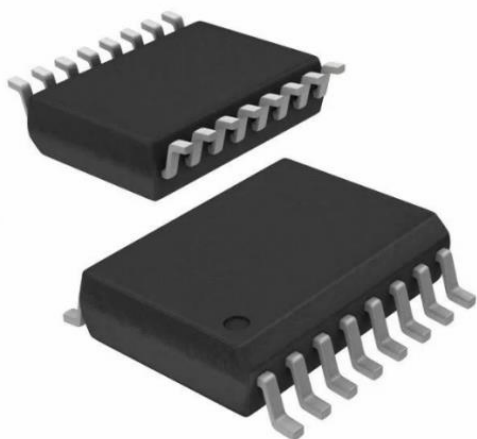
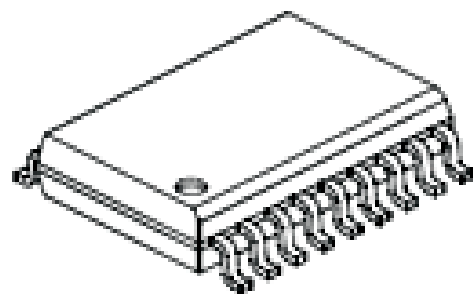


DIP (Dual In-line Package) / PDIP (plastic) / CDIP (ceramic)

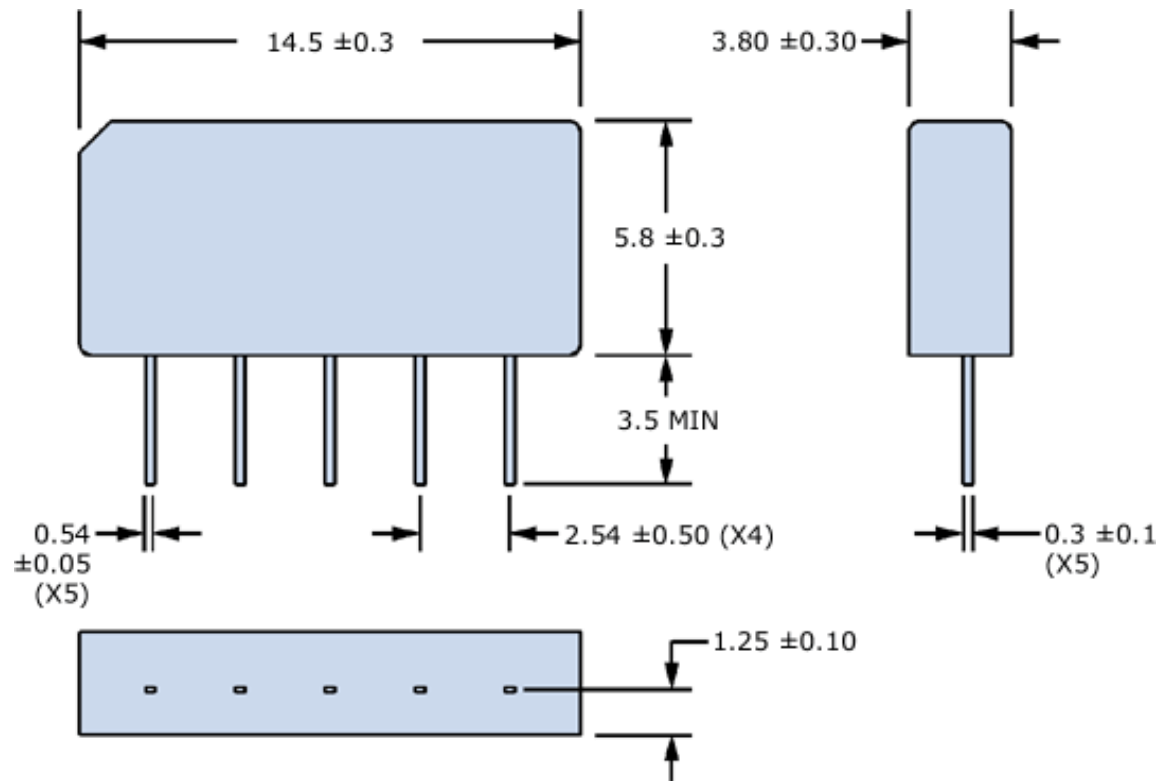
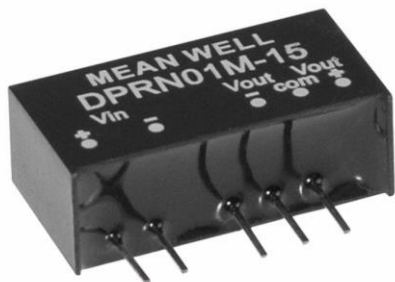
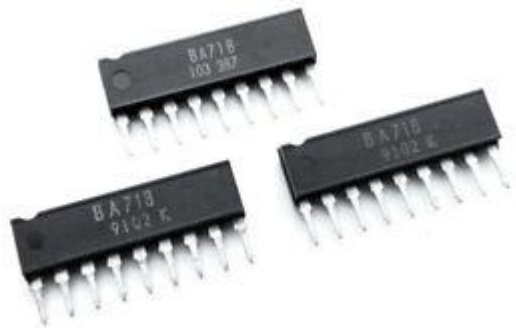
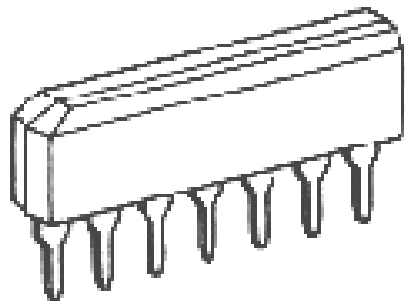
14-pin plastic DIP  
(DIP-14P-M02)



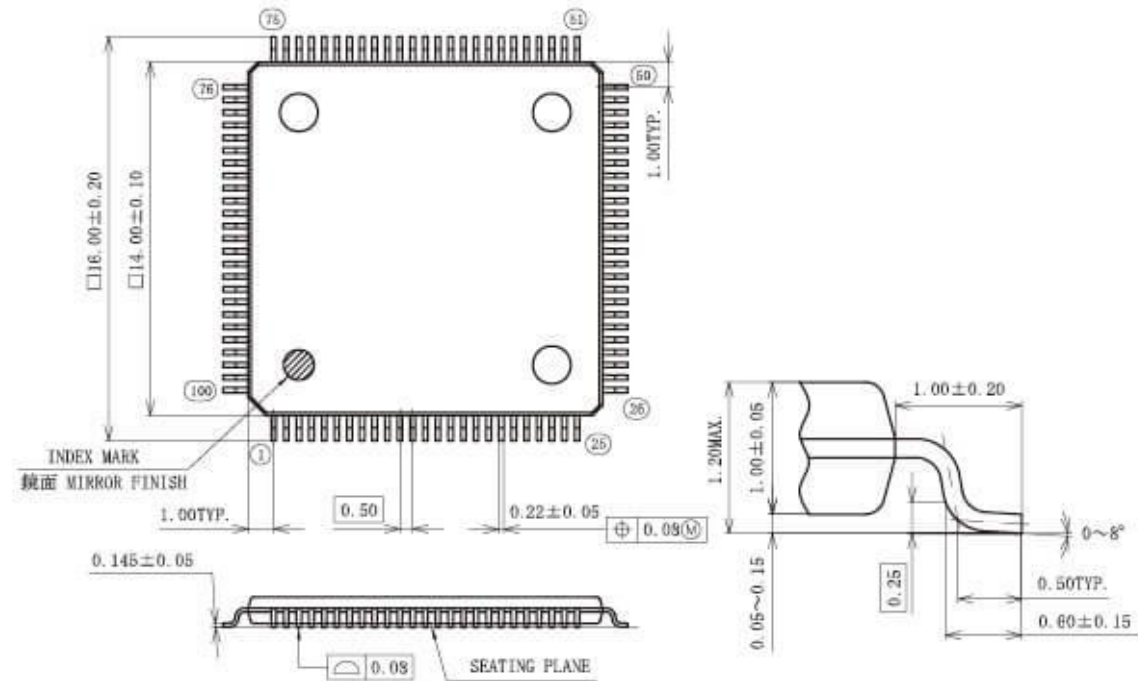
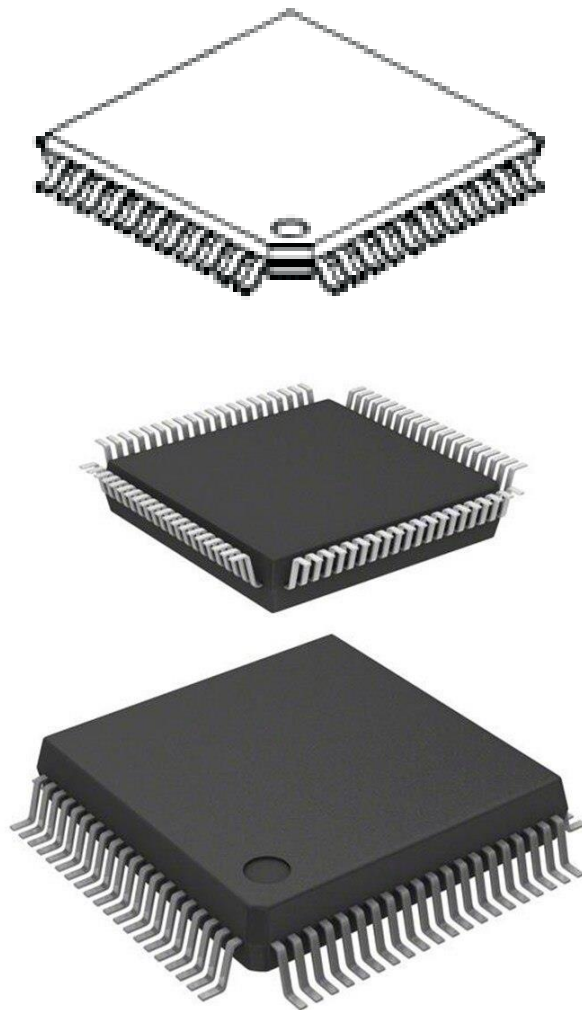
SOIC (Small Outline Integrates Circuit) / SOP (Small Outline Package) / SO



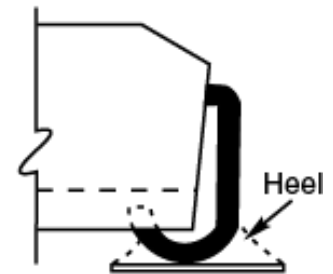
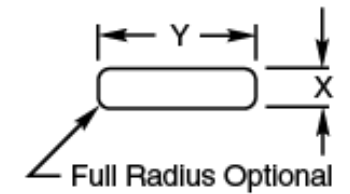
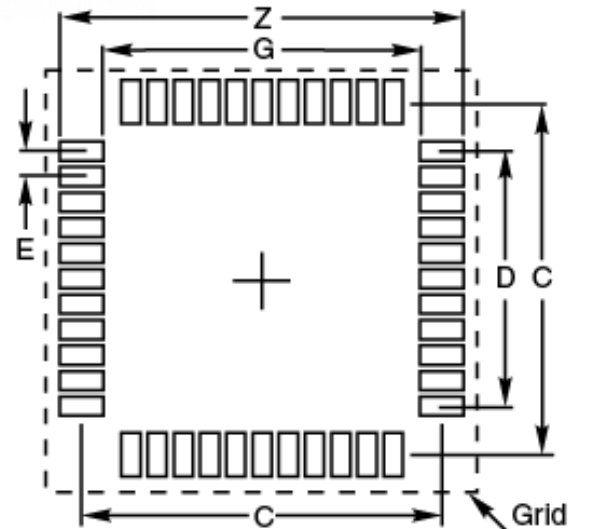
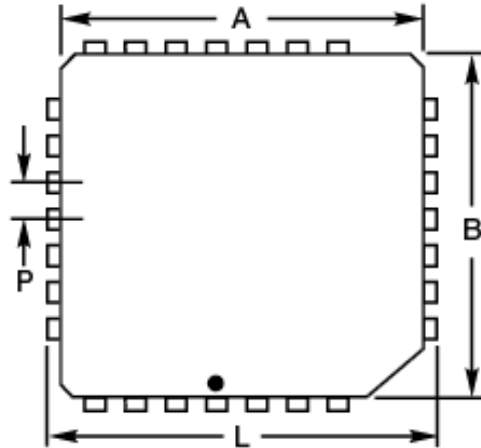
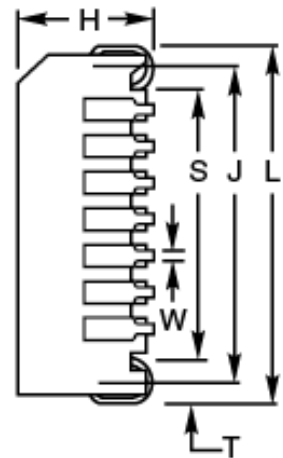
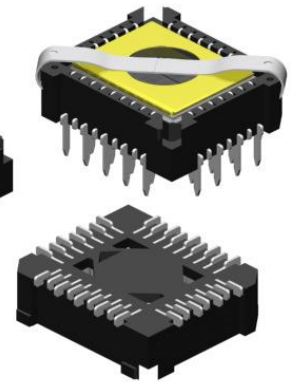
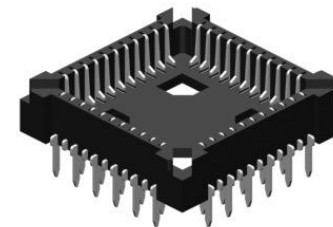
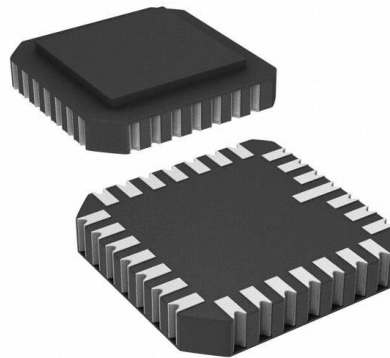
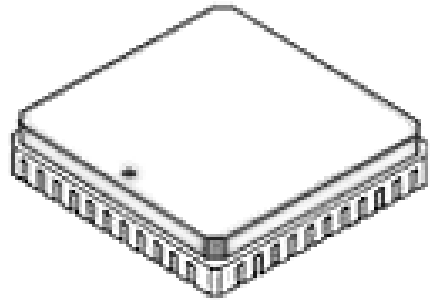
## SIP (Small In-line Package)



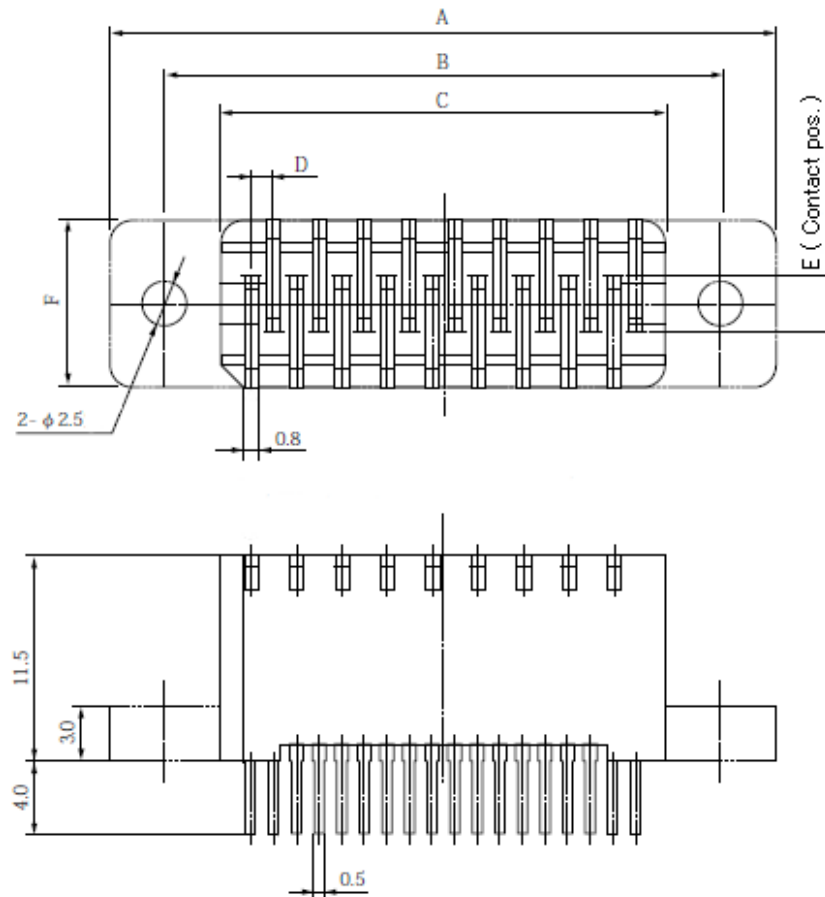
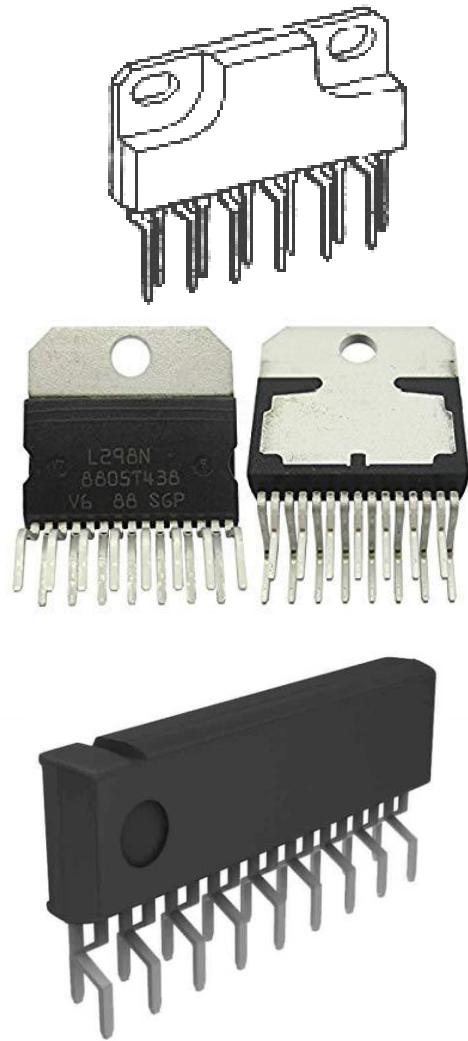
QFP (Quad Flat Package) / TQFP (Thin QFP) / LQFP (Low-profile QFP)



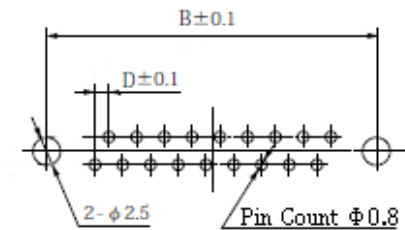
LCC (Leadless Chip Carrier) / PLCC (plastic) / CLCC (ceramic)



## ZIP (Zigzag In-line Package)



### ● PCB Layout (TOP VIEW)







Далі буде...

**...Міжблочні з'єднання в РЕА**